

Product Change Notice (PCN)

Subject: Product Improvement - Transition from projection align to stepper for the HIP4086AW product

Publication Date: 7/6/2018

Effective Date: 10/6/2018

Revision Description:

Initial Release

Description of Change:

The HIP4086AW product is being converted from a projection alignment tool (Perkin Elmer) to a Canon iW Stepper. There is no change to the design, however, there will be a change to the wafer layout. The die count will effectively increase from 1673 to 1685 with this change. See appendix A.

Reason for Change:

This will provide improved productivity through better resource utilization, elimination of alignment test-slices, reduced rework and higher GDPW

Impact on fit, form, function, quality & reliability:

The change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

Product Identification:

Product affected by this change is identifiable via an internal traceability system.

Qualification status: no design change, verification completed.

Sample availability: 7/6/2018

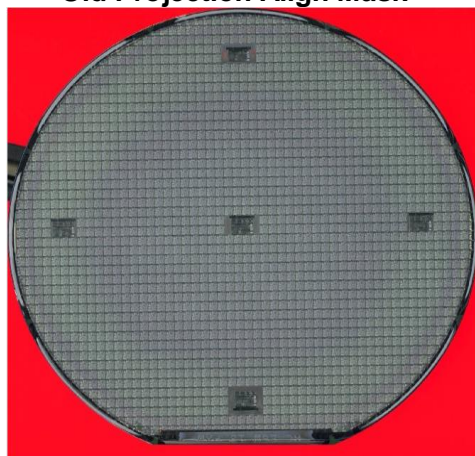
Device material declaration: Available upon request

Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.

For additional information regarding this notice, please contact your regional change coordinator (below)			
Americas: PCN-US@Renesas.COM	Europe: PCN-EU@Renesas.COM	Japan: PCN-JP@Renesas.COM	Asia Pac: PCN-APAC@Renesas.COM

Appendix A – Wafer Layout Difference

Old Projection Align Mask



New Stepper based Mask

